

What is claimed is:

1. A wire bonding capillary for pressing a metal wire against an electrode pad comprising a capillary tip having a pressing face, wherein at least a part of the pressing face of the capillary tip is coated with a layer of polymeric material, said polymeric material including at least one thermoplastic polymer.

2. The wire bonding capillary as in claim 1 wherein said thermoplastic polymer is poly-p-xylylene.

3. A method for preparing a wire bonding capillary comprising the steps of:
(a) providing a wire bonding capillary for pressing a metal wire against an electrode pad comprising a capillary tip having a pressing face; and,
(b) coating at least part of said pressing face of said capillary tip with a layer of polymeric material, said polymeric material including at least one thermoplastic polymer.

4. The method as in claim 5 wherein said thermoplastic polymer is poly-p-xylylene.